

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1564	29/603.07,603.11,603.13-603.17, 417.ccls.	USPAT; JPO; DERWENT	OR	ON	2004/05/26 11:41
S2	3493	360/121,123,126,317,235.7,235.8, 236.3,236.5,236.6,237.ccls.	USPAT; JPO; DERWENT	OR	ON	2004/05/26 11:42
S3	3998	wafer with (slider or transducer or (magnetic adj head))	USPAT; JPO; DERWENT	OR	ON	2004/05/26 13:00
S4	1141	wafer with metalliz\$4	USPAT; JPO; DERWENT	OR	ON	2004/05/26 11:43
S5	43	(wafer with (slider or transducer or (magnetic adj head))) and (wafer with metalliz\$4)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 12:48
S6	2285	wafer with (slider or (magnetic adj head))	USPAT; JPO; DERWENT	OR	ON	2004/05/26 11:56
S7	3	(wafer with metalliz\$4) and (wafer with (slider or (magnetic adj head)))	USPAT; JPO; DERWENT	OR	ON	2004/05/26 12:02
S8	240	360/121,123,126,317,235.7,235.8, 236.3,236.5,236.6,237.ccls. and (wafer with (slider or (magnetic adj head)))	USPAT; JPO; DERWENT	OR	ON	2004/05/26 12:10
S9	1569	29/603.07,603.11,603.13-603.17, 417.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:08
S10	228	360/235.4,234.3,236.5,294.7.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:06
S11	2430	216/39,41,48.ccls.	USPAT; JPO; DERWENT	OR	ON	2004/06/15 15:59
S12	3288	451/5,41.ccls.	USPAT; JPO; DERWENT	OR	ON	2004/06/15 16:00
S15	2079	29/25.35.ccls.	USPAT; JPO; DERWENT	OR	ON	2004/06/15 16:00
S18	1	"4277712".PN.	USPAT	OR	ON	2004/06/15 16:05
S19	2	"5920523".URPN.	USPAT	OR	ON	2004/06/15 16:05
S20	7	("4551647"   "4641153"   "4819014"   "4937597"   "5057664"   "5072240"   "5210455").PN.	USPAT	OR	ON	2004/06/15 16:07

S53	22	silicon adj slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 12:48
S54	77	wafer with silicon with slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:03
S55	88	S53 or S54	USPAT; JPO; DERWENT	OR	ON	2005/03/01 12:50
S56	19	S55 and carbide	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:02
S57	21	("4549238"   "5034828"   "5067037"   "5083365"   "5229193"   "5301077"   "5413850"   "5508861"   "5587857"   "5617273"   "5625512"   "5661618"   "5708540"   "5712747"   "5748408"   "5761001"   "5761790"   "5781376"   "5896244"   "6038101"   "6330131").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/01 12:58
S58	11	("5184393"   "5215608"   "5359479"   "5421943"   "5559051"   "5587857"   "5712747"   "5734519"   "5757591"   "5771571"   "5867888").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/01 12:54
S59	11	("4403238"   "4646128"   "4809103"   "4881144"   "5014145"   "5025304"   "5055969"   "5168078"   "5278712"   "5279991"   "5528819").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/01 12:56
S60	19	("5712747").URPN.	USPAT	OR	ON	2005/03/01 12:57
S61	16	S57 and carbide	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:01
S62	9	S53 and carbide	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:02
S63	3	wafer with silicon with slider with trench\$2	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:04
S64	38	fill\$3 with trench\$2 with carbide	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:05
S65	1	S53 and S64	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:04
S66	129	slider with trench\$2	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:04

S67	1	S64 and S66	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:04
S68	2343	fill\$3 with trench\$2 with (carbide or nitride)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:49
S69	1	S66 and S68	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:05
S70	0	fill\$3 with trench\$2 with (carbide or nitride) with slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:05
S71	0	fill\$3 with trench\$2 with (carbide or nitride) same slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:05
S72	0	360/235.4,234.3,236.5,294.7.ccls. with slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:06
S73	233	360/235.4,234.3,236.5,294.7.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:06
S74	188	S73 and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:10
S75	0	S68 and S74	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:06
S76	2	S68 and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:10
S77	385	29/603.07,603.11,603.13-603.17, 417.ccls. and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:08
S78	0	S68 and S77	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:08
S79	8003	trench\$2 with (carbide or nitride)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:08
S80	1	S77 and S79	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:09
S81	0	S73 and S79	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:09
S82	233	S73 and "360"/\$.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:09

S83	188	S82 and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:42
S84	8	S79 and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:10
S85	10	lille-jeffrey-s.in.	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:12
S86	1	S79 and S85	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:13
S87	3	S66 and S85	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:13
S88	10	("4582632"   "5400192"   "5711063"   "5783326"   "5793571"   "5825590"   "5894655"   "6005750"   "6245313"   "6359752").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/01 13:14
S89	12	slider with (trench\$2 or hole or gap) with (carbide or nitride)	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/01 13:15
S90	34	slider with (fill\$3 or coat\$3) with (carbide or nitride)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:39
S91	24	S90 and @ad<"19990820"	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:25
S92	9	S90 and @ad>"19990820"	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:24
S93	11	216/65.ccls. and etch\$3 and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:40
S94	0	S79 and S93	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:40
S95	5483	etch\$3 with wafer with (trench\$3 or gap or hole)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:41
S96	3887	fill\$3 with (trench\$2 or hole or gap) with (carbide or nitride)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:41
S97	4582	(fill\$3 or coat\$3) with (trench\$2 or hole or gap) with (carbide or nitride)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:42

S98	421	S95 and S97	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:42
S99	2	S98 and slider	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:43
S10 0	0	451/5,41.ccls. and (planariz\$3 with carbide)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:44
S10 1	1	451/5,41.ccls. and (planariz\$3 with slider)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:44
S10 2	16	S57 and (carbide or nitride)	USPAT; JPO; DERWENT	OR	ON	2005/03/01 13:49

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Kurosawa, M.; Takahashi, N.; Higuchi, T.;

Ultrasonics Symposium, 1994. Proceedings., 1994 IEEE , Volume: 1 , 1-4 Nov 1994

Pages:535 - 538 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(256 KB\)\]](#) IEEE CNF
2 **Ultrasonic linear motor using surface acoustic waves**

Kurosawa, M.; Takahashi, M.; Higuchi, T.;

Ultrasonics, Ferroelectrics and Frequency Control, IEEE Transactions on , Volume: 43 , Issue: 5 , Sept. 1996

Pages:901 - 906

[\[Abstract\]](#) [\[PDF Full-Text \(812 KB\)\]](#) IEEE JNL
3 **Frictional behavior of magnetic recording disks**

Trauner, D.; Li, Y.; Talke, F.E.;

Magnetics, IEEE Transactions on , Volume: 26 , Issue: 1 , Jan 1990

Pages:150 - 152

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4 **Measurement of Young's modulus on microfabricated structures using surface profiler**

Tai, Y.-C.; Muller, R.S.;

Micro Electro Mechanical Systems, 1990. 'Proceedings, An Investigation of Micro Structures, Sensors, Actuators, Machines and Robots'. , IEEE , 11-14 Feb. 1990

Pages:147 - 152